AUTOMOTIVE

ROHS

HALOGEN

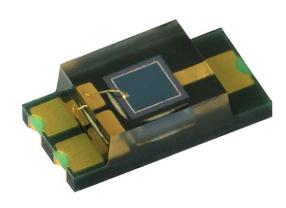
FREE GREEN

(5-2008)



## Vishay Semiconductors

## Silicon PIN Photodiode



#### **DESCRIPTION**

VEMD6060X01 is a high speed and high sensitive PIN photodiode with excellent  $I_{ra}$  linearity. It is a small surface mount device (SMD) including the chip with a 0.85 mm<sup>2</sup> sensitive area detecting visible and near infrared radiation.

#### **FEATURES**

Package type: surface mount

• Package form: 1206

- Dimensions (L x W x H in mm): 4 x 2 x 1.05
- Radiant sensitive area (in mm<sup>2</sup>): 0.85
- · High photo sensitivity
- · High radiant sensitivity
- Excellent I<sub>ra</sub> linearity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity:  $\varphi = \pm 70^{\circ}$
- Floor life: 72 h, MSL 4, according to J-STD-020
- Lead (Pb)-free reflow soldering
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- · High speed photo detector
- · Small signal detection
- · Proximity sensors

PRODUCT SUMMARY				
COMPONENT	I <sub>ra</sub> (μΑ)	φ (deg)	λ <sub>0.1</sub> (nm)	
VEMD6060X01	5	± 70	380 to 1070	

#### Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VEMD6060X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	1206		

### Note

· MOQ: minimum order quantity

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V <sub>R</sub>	20	V	
Power dissipation	T <sub>amb</sub> ≤ 25 °C	P <sub>V</sub>	215	mW	
Junction temperature		Tj	110	°C	
Operating temperature range		T <sub>amb</sub>	-40 to +110	°C	
Storage temperature range		T <sub>stg</sub>	-40 to +110	°C	
Soldering temperature	According to reflow solder profile fig. 8	T <sub>sd</sub>	260	°C	
Thermal resistance junction / ambient	According to EIA / JESD51	R <sub>thJA</sub>	270	K/W	

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 50 mA	$V_{F}$	-	0.85	1.1	V
Breakdown voltage	I <sub>R</sub> = 100 μA, E = 0	V <sub>(BR)</sub>	20	-	-	V
Reverse dark current	V <sub>R</sub> = 10 V, E = 0	I <sub>ro</sub>	-	0.03	5	nA
Diode capacitance	$V_R = 0 V, f = 1 MHz, E = 0$	$C_D$	-	11	=	pF
	V <sub>R</sub> = 5 V, f = 1 MHz, E = 0	$C_D$	-	4.8	=	pF
Open circuit voltage	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	Vo	-	360	-	mV
Temperature coefficient of Vo	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	TK <sub>Vo</sub>	-	-3.1	-	mV/K
Short circuit current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	I <sub>k</sub>	-	5	-	μA
Temperature coefficient of I <sub>k</sub>	$E_e = 1 \text{ mW/cm}^2, \lambda = 835 \text{ nm}$	TK <sub>lk</sub>	-	0.1	-	%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2$ , $\lambda = 950 \text{ nm}$ , $V_R = 5 \text{ V}$	I <sub>ra</sub>	3.5	5	6.5	μA
	$E_e = 1 \text{ mW/cm}^2$ , $\lambda = 890 \text{ nm}$ , $V_R = 5 \text{ V}$	I <sub>ra</sub>	-	7	-	μΑ
Angle of half sensitivity		φ	-	± 70	-	deg
Wavelength of peak sensitivity		$\lambda_{p}$	-	820	-	nm
Range of spectral bandwidth		λ <sub>0.1</sub>	-	380 to 1070	=	nm
Rise time	$V_R = 10 \text{ V}, R_L = 50 \Omega, \lambda = 830 \text{ nm}$	t <sub>r</sub>	-	60	=	ns
Fall time	$V_R = 10 \text{ V}, R_L = 50 \Omega, \lambda = 830 \text{ nm}$	t <sub>f</sub>	-	50	-	ns

## **BASIC CHARACTERISTICS** (T<sub>amb</sub> = 25 °C, unless otherwise specified)

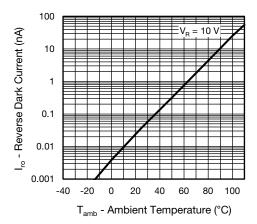


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

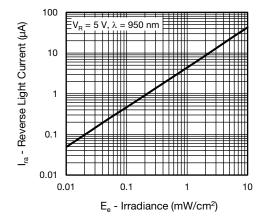


Fig. 3 - Reverse Light Current vs. Irradiance

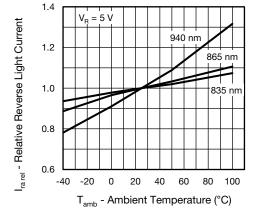


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

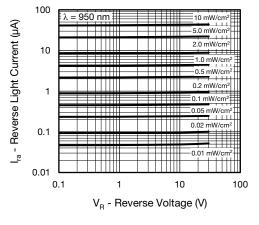


Fig. 4 - Reverse Light Current vs. Reverse Voltage

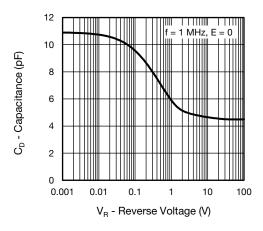


Fig. 5 - Diode Capacitance vs. Reverse Voltage

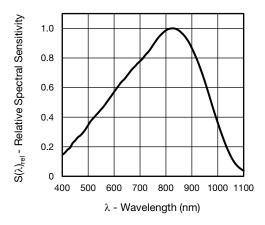


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

## **REFLOW SOLDER PROFILE**

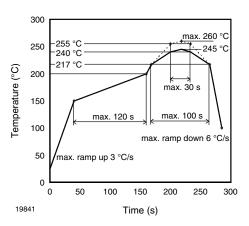


Fig. 8 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

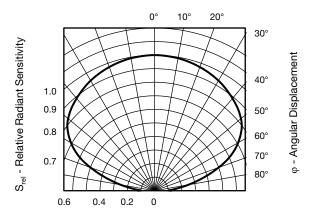


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

### **DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

### **FLOOR LIFE**

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 72 h

Conditions:  $T_{amb}$  < 30 °C, RH < 60 %

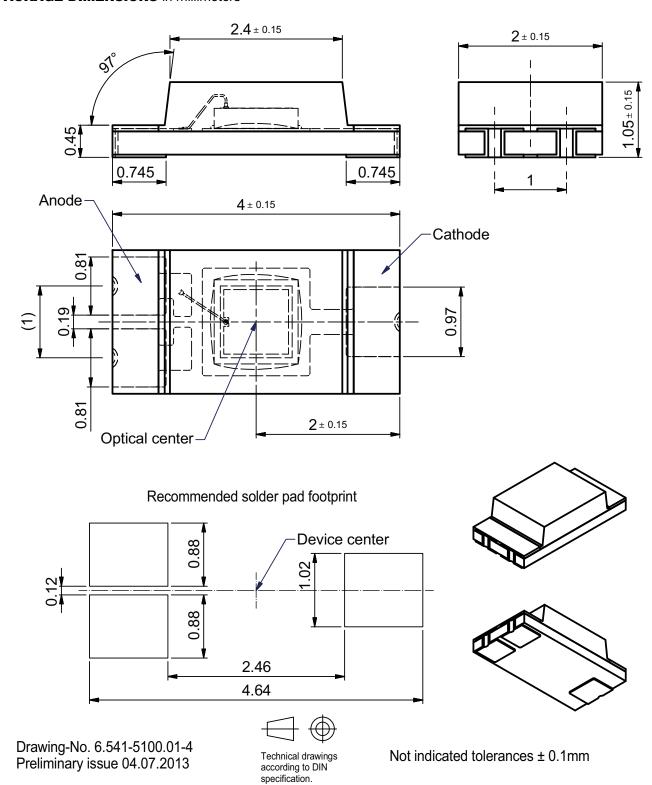
Moisture sensitivity level 4, according to J-STD-020.

w.vishav.com/doc?91000

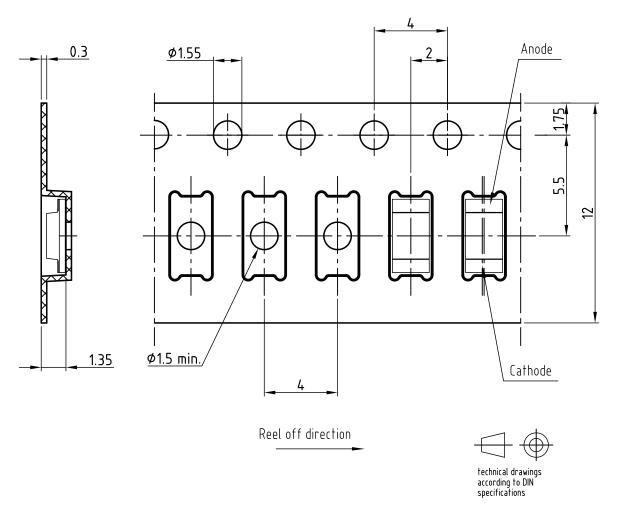
#### **DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

### **PACKAGE DIMENSIONS** in millimeters



### **BLISTER TAPE DIMENSIONS** in millimeters



Not indicated tolerances ±0.1

Drawing refers to following Types: TEMD6010FX01

VEMD6x10X01

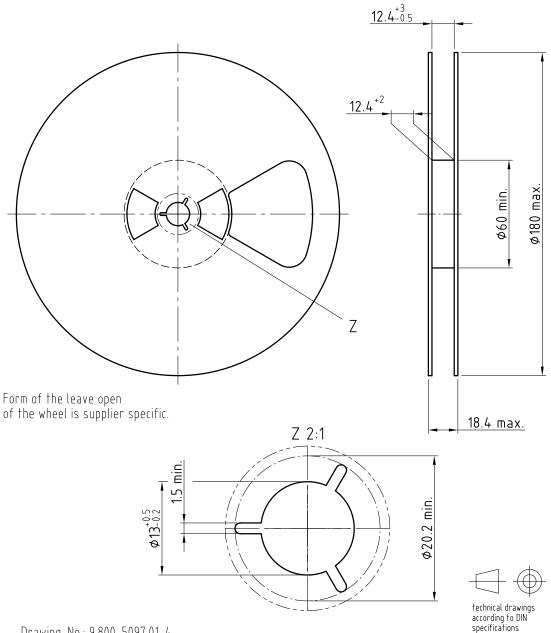
Drawing-No.: 9.700-5329.02-4

Prel Issue: 16.07.2013

VEMD6x15X01

All dimensions in mm

### **REEL DIMENSIONS** in millimeters



Drawing-No.: 9.800-5097.01-4

Issue: 1; 05.05.08

20874



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